



## ABSOLUTE MAXIMUM RATINGS

These are stress ratings only and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications below is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

Supply Voltage ( $V_{IN}$ ).....7.0V  
 Fault Flag Voltage ( $V_{FLAG}$ ).....7.0V  
 Fault Flag Current ( $I_{FLAG}$ ).....50mA  
 Enable Control Input ( $V_{EN}$ ).....-0.3V -15V

Operating Temperature Range.....-40°C to +85°C  
 Junction Temperature Range.....125°C  
 Storage Temperature Range.....-65°C to +150°C  
 Lead Temperature (10 sec. soldering).....260°C  
 Power Dissipation Per Package  
 8-pin NSOIC (derate 6.14mW/°C above +70°C).....500mW

## ELECTRICAL CHARACTERISTICS

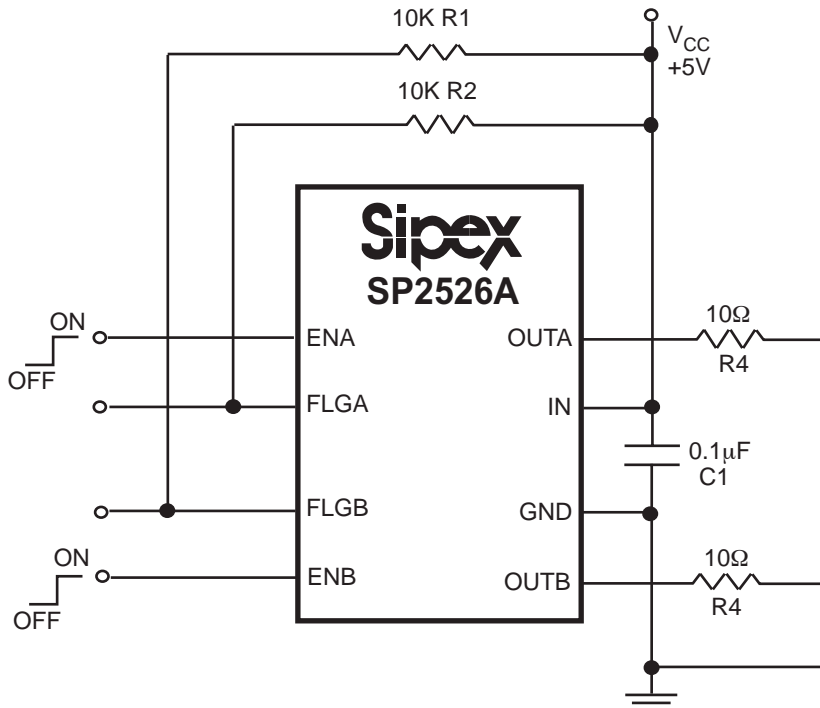
Unless otherwise noted, the following specifications apply for  $V_{IN} = +5.0V$ ,  $T_A = 25^\circ C$ .

PARAMETER	MIN.	TYP.	MAX.	UNITS	CONDITIONS
Supply Current		0.75 110	5.0 160	$\mu A$	$V_{EN} = \text{Logic "0"}$ OUT = Open $V_{EN} = \text{Logic "1"}$ OUT = Open
Enable Input Voltage	2.4	1.7 2.0	0.8	V	$V_{EN} = \text{Logic "0"}$ $V_{EN} = \text{Logic "1"}$
Enable Input Current		0.01 0.01	1 1	$\mu A$	$V_{EN} = \text{Logic "0"}$ $V_{EN} = \text{Logic "1"}$
Enable Input Capacitance		1		pF	
Output Mosfet Resistance		110	150	m $\Omega$	
Output Turn-On Delay		100		$\mu s$	$R_L = 10\Omega$ each output
Output Turn-On Rise Time		1000	4000	$\mu s$	$R_L = 10\Omega$ each output
Output Turn-Off Delay		0.8	20	$\mu s$	$R_L = 10\Omega$ each output
Output Turn-Off Fall Time		0.7	20	$\mu s$	$R_L = 10\Omega$ each output
Output Leakage Current			10	$\mu A$	
Current Limit Threshold	0.6	1.0	1.25	A	
Over-Temperature Shutdown Threshold		135 125		$^\circ C$	$T_J$ increasing $T_J$ decreasing
Error Flag Output Resistance		10 15	25 40	$\Omega$	$V_{IN} = 5V, I_L = 10mA$ $V_{IN} = 3.3V, I_L = 10mA$
Error Flag Off Current		0.01	1	$\mu A$	$V_{FLAG} = 5V$
UVLO Threshold		2.6 2.4		V	$V_{IN}$ increasing $V_{IN}$ decreasing

## PIN DESCRIPTION

Pin Number	Pin Name	Description
1	ENA	Enable Input for MOSFET Switch A. This input pin is active high for the SP2526A-1 and active low for the SP2526A-2
2	FLGA	An active-low and open-drained fault flag output for channel A. It can indicate current limit when ENA is active. In normal mode operation (ENA or/and ENB is active), it also can indicate thermal shutdown or undervoltage.
3	FLGB	An active-low and open-drained fault flag output for channel B. It can indicate current limit when ENB is active. In normal mode operation (ENA or/and ENB is active), it also can indicate thermal shutdown or undervoltage.
4	ENB	Enable Input for MOSFET Switch B. This input pin is active high for the SP2526A-1 and active low for the SP2526A-2
5	OUTB	Output for MOSFET Switch Channel B. This is the output pin of the MOSFET source of channel B, typically connected to the switched side of the load.
6	GND	Ground.
7	IN	Power supply input
8	OUTA	Output for MOSFET Switch Channel A. This is the output pin of the MOSFET source of channel A, typically connected to the switched side of the load.

## TEST CIRCUIT



### Error Flag

An open-drained output of an N-channel MOSFET, the FLG output is pulled low to signal the following fault conditions: input undervoltage, output current limit, and thermal shutdown.

### Current Limit

The current limit threshold is preset internally. It protects the output MOSFET switches from damage resulting from undesirable short circuit conditions or excess inrush current, which is often encountered during hot plug-in. The low limit of the current limit threshold of the SP2526A allows a minimum current of 0.6A through the MOSFET switches. A current limit condition will signal the error flag.

### Thermal Shutdown

When the chip temperature exceeds 135°C for any reason other than overcurrent fault of either one of the two MOSFETs, the thermal shutdown function turns off both MOSFET switches and signals the error flag. A hysteresis of 10°C prevents the MOSFETs from turning back on until the chip temperature drops below 125°C. However, if thermal shutdown is triggered by chip temperature rise resulting from overcurrent fault condition of either one of the MOSFET switches, the thermal shutdown function will only turn off the switch that is in overcurrent condition and the other switch can still remain its normal operation. In other words, the thermal shutdown function of the two switches is independent of each other in the case of overcurrent fault.

### Supply Filtering

A 0.1 $\mu$ F to 1 $\mu$ F bypass capacitor from IN to GND, located near the device, is strongly recommended to control supply transients. Without a bypass capacitor, an output short may cause sufficient ringing on the input (from supply lead inductance) to damage internal control circuitry.

### Transient Requirements

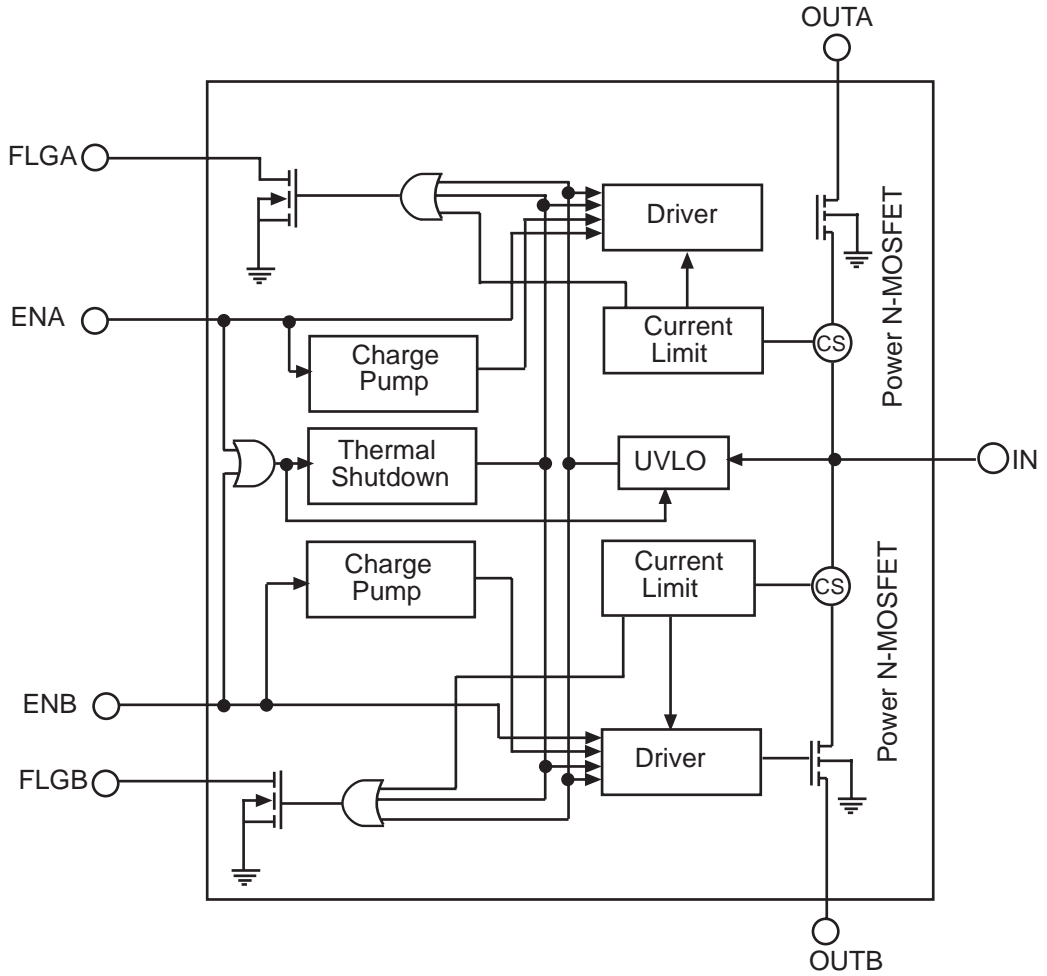
USB supports dynamic attachment (hot plug-in) of peripherals. A current surge is caused by the input capacitance of downstream device. Ferrite beads are recommended in series with all power and ground connector pins. Ferrite beads reduce EMI and limit the inrush current during hot-attachment by filtering high-frequency signals.

### Short Circuit Transient

Bulk capacitance provides the short-term transient current needed during a hot-attachment event. A 33  $\mu$ F, 16V tantalum or a 100 $\mu$ F, 10V electrolytic capacitor mounted close to downstream connector each port should provide transient drop protection

### Printed Circuit Layout

The Power circuitry of USB printed circuit boards requires a customized layout to maximize thermal dissipation and to minimize voltage drop and EMI.



# TYPICAL PERFORMANCE CHARACTERISTICS

$V_{IN} = +5.0V$ , single MOSFET switch section, and  $T_{AMB} = +25^{\circ}C$  unless otherwise noted.

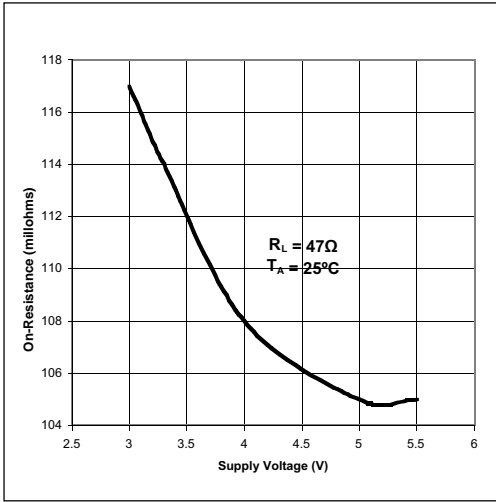


Figure 1. Output On-Resistance vs. Supply Voltage

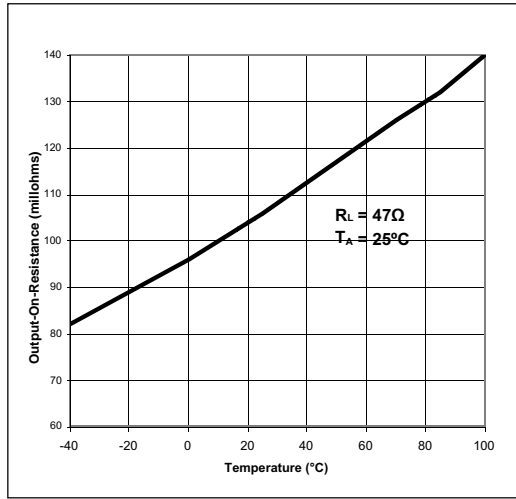


Figure 2. Output On-Resistance vs. Temperature

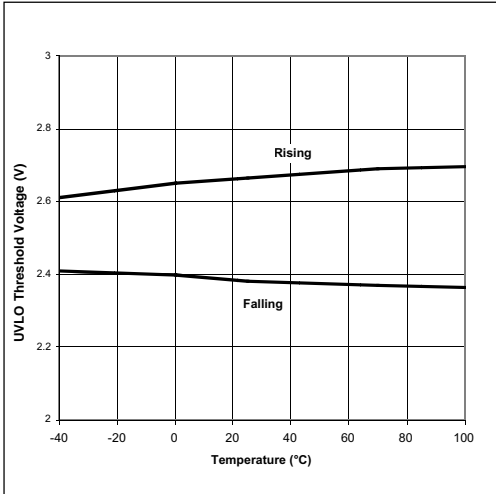


Figure 3. UVLO Threshold Voltage vs. Temperature

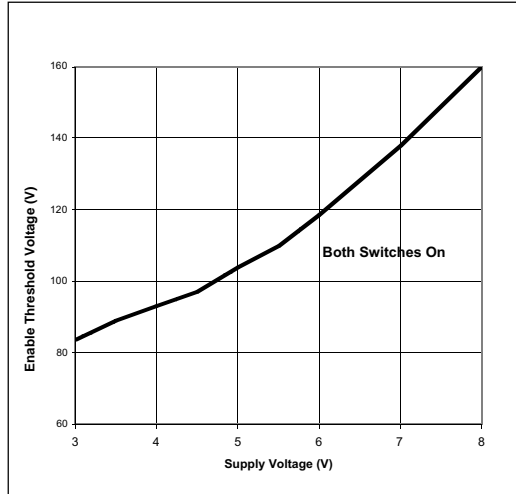


Figure 4. On-state Supply Current vs. Supply Voltage

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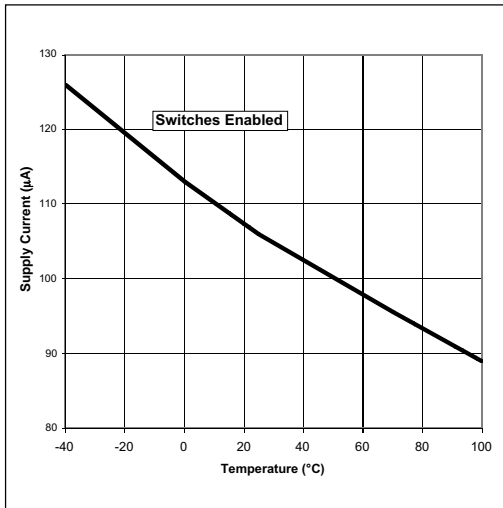


Figure 5. On-state Supply Current vs. Temperature

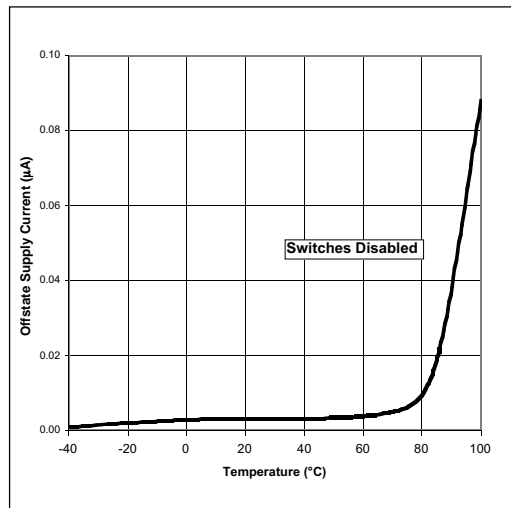


Figure 6. Off-state Supply Current vs. Temperature

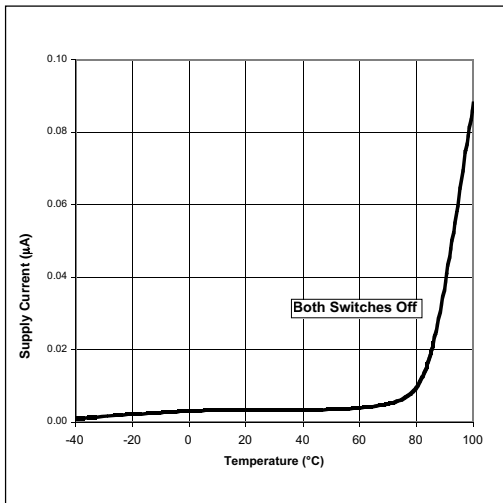


Figure 7. Off-state Supply Current vs. Supply Voltage

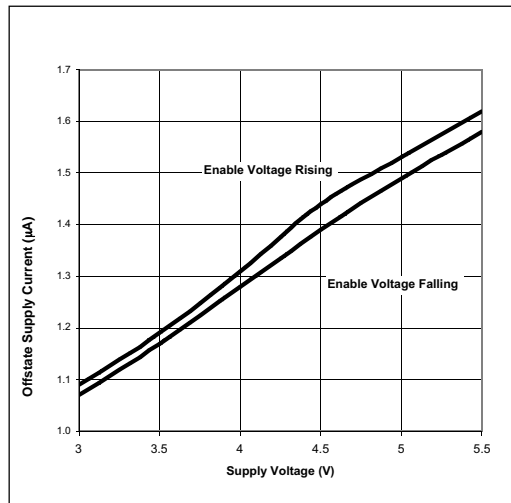


Figure 8. Control Threshold vs. Supply Voltage

## TYPICAL PERFORMANCE CHARACTERISTICS

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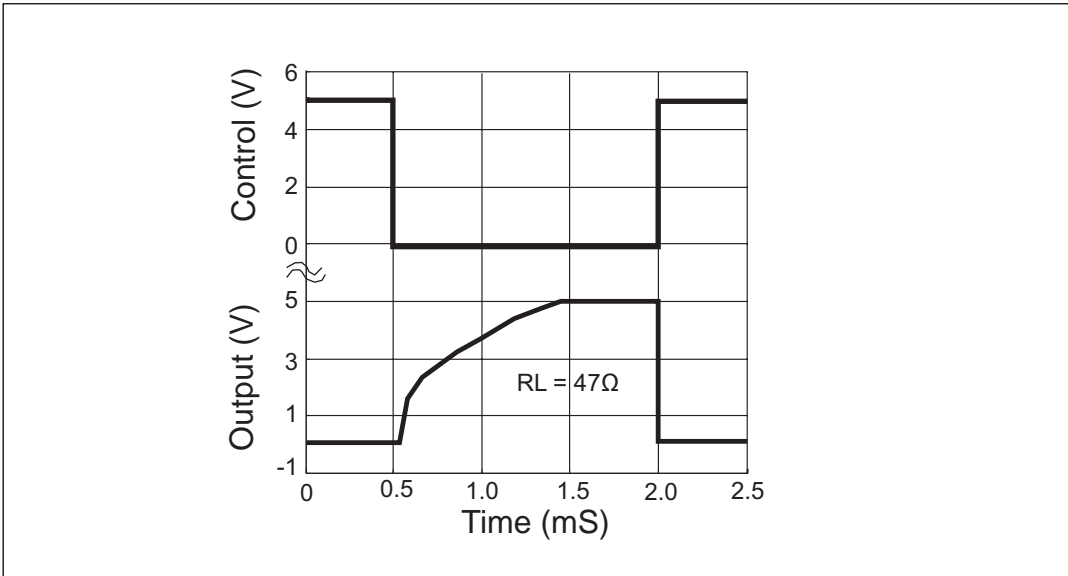
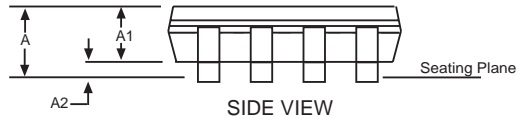
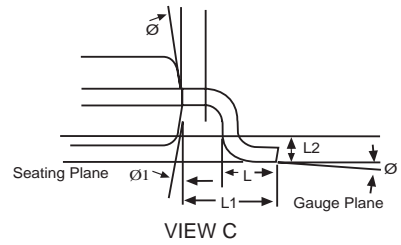
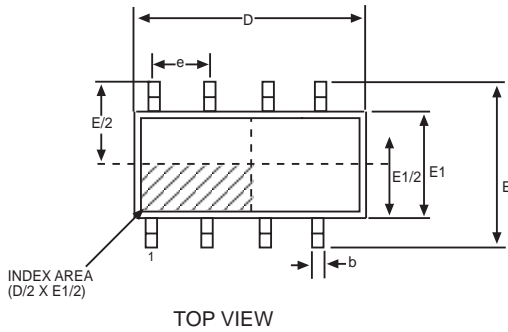


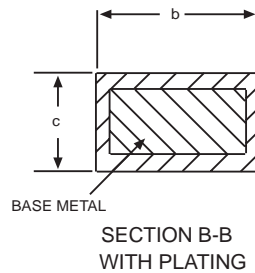
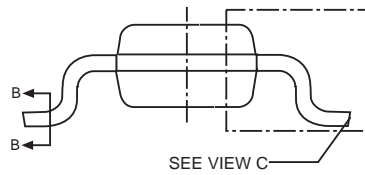
Figure 9. Turn-on/Turn-off Characteristics





8 Pin NSOIC JEDEC MO-012 (AA) Variation			
SYMBOL	MIN	NOM	MAX
A	1.35	-	1.75
A1	0.1	-	0.25
A2	1.25	-	1.65
b	0.31	-	0.51
c	0.17	-	0.24
D	4.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
L	0.4	-	1.27
L1	1.04 REF		
L2	0.25 BSC		
ø	0°	-	8°
ø1	5°	-	15°

Note: Dimensions in (mm)



## ORDERING INFORMATION

Part Number	Temperature Range	Package Types
SP2526A-1EN .....	-40°C to +85°C .....	8-pin NSOIC
SP2526A-1EN/TR .....	-40°C to +85°C .....	8-pin NSOIC
SP2526A-2EN .....	-40°C to +85°C .....	8-pin NSOIC
SP2526A-2EN/TR .....	-40°C to +85°C .....	8-pin NSOIC

Available in lead free packaging. To order add "-L" suffix to part number.

Example: SP2526A-1EN/TR = standard; SP2526A-1EN-L/TR = lead free

/TR = Tape and Reel

Pack quantity is 2,500 for NSOIC.

 [CLICK HERE TO ORDER SAMPLES](#)



ANALOG EXCELLENCE

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